



Material Content Data Sheet



Sales Product Name	TLE4961-1M			Issued	22. January 2018			
MA#	MA001227992							
Package	PG-SOT23-3-15			Weight*	9.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35595	35595
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365592	367133
	noble metal	gold	7440-57-5	0.019	0.19	0.19	1890	1890
	encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5463
encapsulation	plastics	epoxy resin	-	1.153	11.75		117454	
	inorganic material	silicondioxide	60676-86-0	4.157	42.33	54.63	423381	546298
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15240	15240
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15133	15133
glue	plastics	epoxy resin	-	0.032	0.33		3274	
	noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18711
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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